WHAT IS CLAIMED IS:

1. An optocoupler package comprising:

(a) a substrate comprising a leadframe and a molding compound;

(b) an optical emitter;

(c) an optical receiver, wherein the optical emitter and the optical receiver are electrically coupled to the leadframe; and

(d) an optically transmissive medium disposed between the optical emitter and optical receiver.

2. The optocoupler package of claim 1 further comprising a plurality of conductive structures coupled to the leadframe, wherein the conductive structures have heights greater than the heights of the optical receiver and the optical emitter.

3. The optocoupler package of claim 2 wherein the conductive structures are solder structures.

4. The optocoupler package of claim 1 further comprising bond wires electrically coupling the optical receiver to the leadframe and electrically coupling the optical emitter to the leadframe.

5. The optocoupler package of claim 1 wherein the leadframe includes a etched portions and non-etched portions, and wherein the etched portions are covered by the molding compound and the non-etched portions are not covered by the molding compound.

6. The optocoupler package of claim 1 wherein the leadframe comprises copper.

7. The optocoupler package of claim 1 wherein a plurality of optocouplers are on the substrate.

8. The optocoupler package of claim wherein the leadframe includes a etched portions and non-etched portions at a first side, and wherein the etched portions are covered by the molding compound and the non-etched portions are not covered by the molding compound, and wherein the molding compound completely covers the second side of the leadframe.

9. A method for forming an optocoupler package comprising:

(a) forming a substrate comprising a leadframe and a molding compound;

(b) attaching an optical emitter and an optical receiver to the substrate; and

(c) depositing a light transmissive material between the optical emitter and the optical receiver.

10. The method of claim 9 further comprising:

forming a plurality of conductive structures on the substrate, wherein the conductive structures have heights greater than the heights of the optical emitter and optical receiver.

11. The method of claim 9 wherein the method comprises, prior to (a), etching the leadframe.

12. The method of claim 9 wherein the leadframe comprises copper.

13. The method of claim 9 further comprising attaching wires from the optical emitter and the optical receiver to the leadframe.

14. The method of claim 9 further comprising depositing an opaque material on the light transmissive material.

15. The method of claim 9 further comprising attaching at least four optical emitters and at least four optical receivers on the substrate.

16. An optocoupler package comprising:

(a) a substrate; and

(b) at least two optical emitters;

(c) at least two optical receivers;

(d) optically transmissive media between adjacent optical emitters and optical receivers; and

(e) a light reflective material on the optically transmissive media,

wherein the optical emitters and the optical receivers are on the substrate.

17. The optocoupler package of claim 16 wherein the substrate includes a leadframe including etched portions.

18. The optocoupler package of claim 16 wherein the substrate comprises a leadframe that includes copper and a molding compound.

19. The optocoupler package of claim 16 further comprising a chip including a MOSFET on the substrate.

20. The optocoupler package of claim 1 further comprising a chip including a MOSFET on the substrate.